

FGA50N100BNTD 1000V, 50A NPT-Trench IGBT CO-PAK

General Description

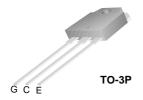
Trench insulated gate bipolar transistors (IGBTs) with NPT technology show outstanding performance in conduction and switching characteristics as well as enhanced avalanche ruggedness. These devices are well suited for Induction Heating (I-H) applications

Features

- High Speed Switching
- Low Saturation Voltage : $V_{CE(sat)} = 2.5 \text{ V} @ I_C = 60 \text{A}$
- High Input Impedance
- Built-in Fast Recovery Diode

Application

Micro- Wave Oven, I-H Cooker, I-H Jar, Induction Heater, Home Appliance





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

| Symbol | Description | | FGA50N100BNTD | Units |
|---------------------|---|--------------------------|---------------|-------|
| V _{CES} | Collector-Emitter Voltage | | 1000 | V |
| V _{GES} | Gate-Emitter Voltage | | ± 25 | V |
| | Collector Current | @ $T_C = 25^{\circ}C$ | 50 | Α |
| IC | Collector Current | @ T _C = 100°C | 35 | Α |
| I _{CM (1)} | Pulsed Collector Current | | 200 | Α |
| I _F | Diode Continuous Forward Current | @ T _C = 100°C | 15 | Α |
| P_{D} | Maximum Power Dissipation | @ $T_C = 25^{\circ}C$ | 156 | W |
| | Maximum Power Dissipation | @ T _C = 100°C | 63 | W |
| TJ | Operating Junction Temperature | | -55 to +150 | °C |
| T _{stg} | Storage Temperature Range | | -55 to +150 | °C |
| TL | Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds | | 300 | °C |

Notes

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

| Symbol | Parameter | Тур. | Max. | Units | |
|------------------------|---|------|------|-------|--|
| $R_{\theta JC}(IGBT)$ | Thermal Resistance, Junction-to-Case | | 0.8 | °C/W | |
| $R_{\theta JC}(DIODE)$ | Thermal Resistance, Junction-to-Case | | 2.4 | °C/W | |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | | 25 | °C/W | |

Package Marking and Ordering Information

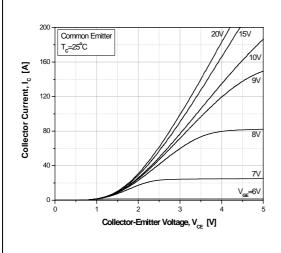
| Device Marking | | Device | Package | Packaging Type | Qty per Tube | Max Qty per Box |
|----------------|-------------------------------|--------|---------|----------------|--------------|--------------------|
| | FGA50N100BNTD FGA50N100BNTDTU | | TO-3PN | Rail / Tube | 30ea | - |

Electrical Characteristics of IGBT T_C = 25°C unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Units |
|---------------------|-------------------------------------|---|------|------|-------|-------|
| Off Cha | racteristics | | | | | |
| BV _{CES} | Collector Emitter Breakdown Voltage | $V_{GE} = 0V$, $I_C = 1mA$ | 1000 | | | V |
| I _{CES} | Collector Cut-Off Current | V _{CE} = 1000V, V _{GE} = 0V | | | 1.0 | mA |
| I _{GES} | G-E Leakage Current | $V_{GE} = \pm 25, V_{CE} = 0V$ | | | ± 500 | nA |
| On Chai | racteristics | | | | | |
| $V_{GE(th)}$ | G-E Threshold Voltage | $I_C = 60 \text{mA}, V_{CE} = V_{GE}$ | 4.0 | 5.0 | 7.0 | V |
| | Collector to Emitter | $I_C = 10A$, $V_{GE} = 15V$ | | 1.5 | 1.8 | V |
| $V_{CE(sat)}$ | Saturation Voltage | | 2.5 | 2.9 | V | |
| C _{ies} | C Characteristics Input Capacitance | V _{CE} =10V, V _{GE} = 0V, | | 6000 | | pF |
| | Input Capacitance | V ₀ =10V V ₀ = 0V | | 6000 | | pF |
| C _{oes} | Output Capacitance | f = 1MHz | | 260 | | pF |
| C _{res} | Reverse Transfer Capacitance | | | 200 | | pF |
| Switchi | ng Characteristics | | | ı | | |
| t _{d(on)} | Turn-On Delay Time | $V_{CC} = 600 \text{ V}, I_{C} = 60\text{A},$ | | 140 | | ns |
| t _r | Rise Time | $V_{CC} = 600 \text{ V}, I_C = 600 \text{ A},$ $R_G = 51\Omega, V_{GE} = 15V,$ Resistive Load, $T_C = 25^{\circ}\text{C}$ | | 320 | | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 630 | | ns |
| t _f | Fall Time | 1.00.00.00 2000, 10 = 20 0 | | 130 | 250 | ns |
| Q _a | Total Gate Charge | V COO.V.I. COA | | 275 | 350 | nC |
| Q _{ge} | Gate-Emitter Charge | $V_{CE} = 600 \text{ V}, I_{C} = 60\text{A},$ $V_{GE} = 15\text{V}, T_{C} = 25^{\circ}\text{C}$ | | 45 | | nC |
| Q _{gc} | Gate-Collector Charge | VGE = 13V,, 1C = 23 C | | 95 | | nC |

Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Units |
|-----------------|-------------------------------|--------------------------------------|------|------|------|-------|
| V | Diode Forward Voltage | I _F = 15A | | 1.2 | 1.7 | V |
| V_{FM} | | I _F = 60A | | 1.8 | 2.1 | V |
| t _{rr} | Diode Reverse Recovery Time | I _F = 60A di/dt = 20 A/us | | 1.2 | 1.5 | us |
| IR | Instantaneous Reverse Current | VRRM = 1000V | | 0.05 | 2 | uA |



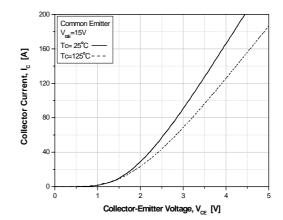
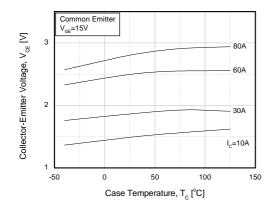


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



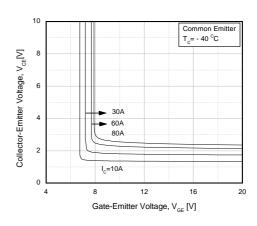
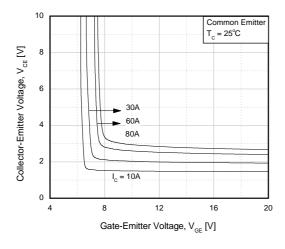


Fig 3. Saturation Voltage vs. Case **Temperature at Varient Current Level**

Fig 4. Saturation Voltage vs. V_{GE}



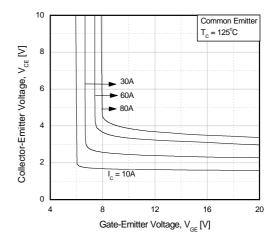
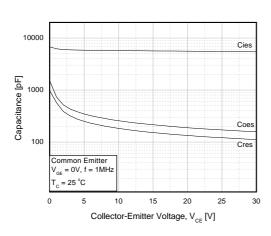


Fig 5. Saturation Voltage vs. V_{GE}

Fig 6. Saturation Voltage vs. V_{GE}



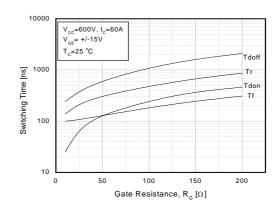
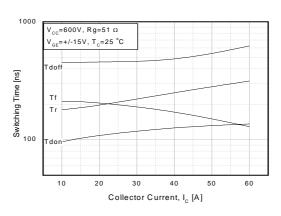


Fig 7. Capacitance Characteristics

Fig 8. Switching Characteristics vs. Gate Resistance



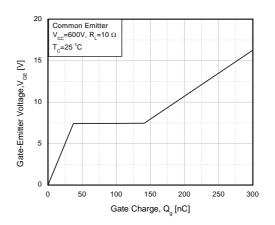
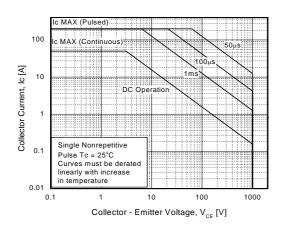


Fig 9. Switching Characteristics vs. Collector Current

Fig 10. Gate Charge Characteristics



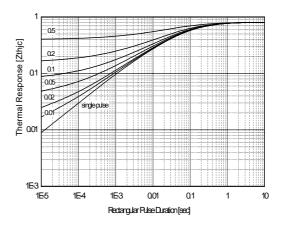


Fig 11. SOA Characteristics

Fig 12. Transient Thermal Impedance of IGBT

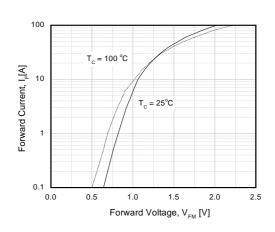


Fig 13. Forward Characteristics

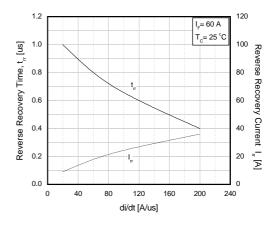


Fig 14. Reverse Recovery Characteristics vs. di/dt

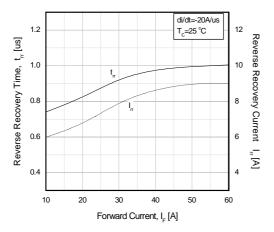


Fig 15. Reverse Recovery Characteristics vs. Forward Current

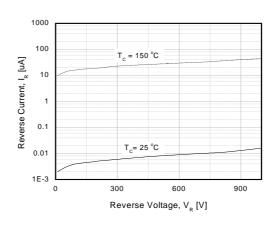


Fig 16. Reverse Current vs. Reverse Voltage

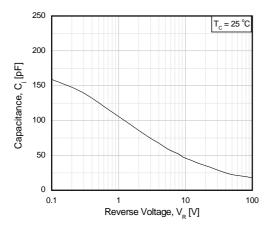
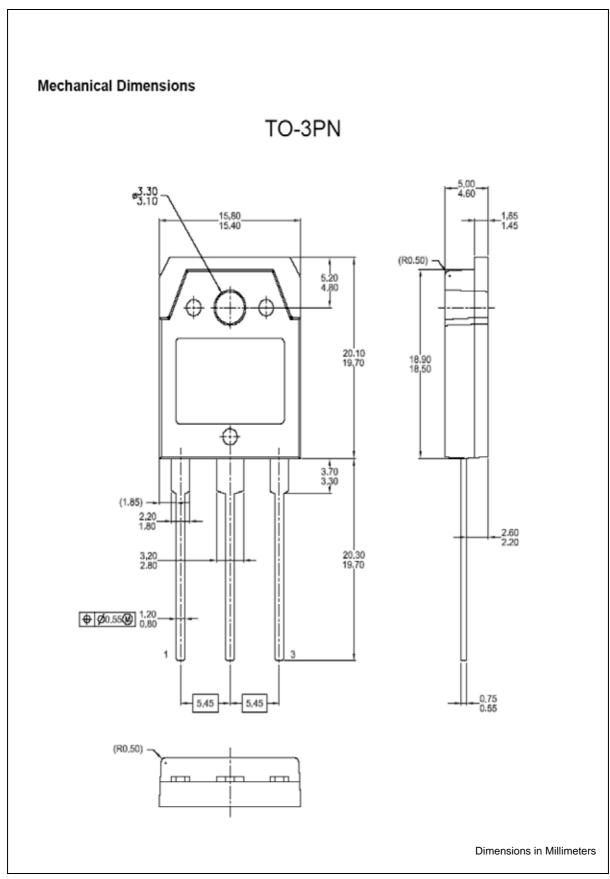


Fig 17. Junction capacitance







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